



EMI PAC-2000 SUBRACK

DATASHEET

FEATURES

- Provides complete EMI/RFI containment
- Provides quick access to the rear of the backplane
- Rackmount or optional mount configurations
- Precision-tooled extrusions
- Provisions for rear plug-in transition modules and cabled rear transition modules (RTMs)
- Available with backplanes installed (VME64x or CompactPCI®)
- Custom hybrid versions available
- IEEE 1101.10/1101.11 compliant
- Backward compatible to ANSI/IEEE 1101.1
- Full range of sizes from 3U x 160 mm to 9U x 400 mm, widths up to 21 slots
- Patented CoolSlot® air deflecting card guides optimize air flow



TABLE 1: TECHNOLOGY OVERVIEW

CONSTRUCTION	
Extrusions	6063-T6 aluminum, precision grade with clear chromate (conductive) plating
Sideplates	.090" thick aluminum, 5052-H32 with clear chromate (conductive) plating
Card Guides	Molded plastic, Noryl N190X Black (Red for cPCI system slot), UL94-V0
Tapped Strips	Carbon steel bar stock with zinc plating and supplementary chromate treatment
ESD Ground Clip	Beryllium Copper, Alloy C17400, 1/2 HT, with Bright Tin plating/MIL-T-10727
Optional Mount (Vertical and horizontal) brackets	16 gauge cold-rolled steel with zinc plating and supplemental clear chromate treatment, .125" thick aluminum, 5052-H32 with clear chromate (conductive) plating
Insertor/Extractor/Fixed Front Panel Handle	Available in VME/VXI, 1101.10 compatible, and Telecom versions